Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	57	(multidie or multi-die or stacked near die or mcm or multi-chip or multichip) near2 package and (chip or die or ic) near2 (wire or wiring or connection or conductor or interconnect or interconnection or bond) near4 (through or thru) near2 (aperture or hole or opening or window)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/25 08:58
L2	9	("20020047214" | "20040089936" | "5324888" | "6335565" | "6353263" | "6424050" | "6455927" | "6548330" | "6791195").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/05/25 09:00
L4	2	"6774473".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/25 09:20
L5	24	(front or top or upper or first or parent or higher) near (chip or die or ic) near3 (bottom or back or lower or second or child or daughter) near (chip or die or ic) near3 (bonded or joined or connection or connected or connecting or wirebond or wirebonded or interconnect$3 or wired) near5 (through or thru) near4 (substrate or interposer or carrier)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/25 09:22
L6	28	(front or top or upper or first or parent or higher) near (chip or die or ic) near3 (bottom or back or lower or second or child or daughter) near (chip or die or ic) near3 (bonded or joined or connection or connected or connecting or wirebond or wirebonded or interconnect$3 or wired) near5 (through or thru) near4 (substrate or interposer or carrier or pcb or pwb or wiring adj board or circuit adj board)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/25 09:25
L7	3	("5903052" | "6104089" | "6184580").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/05/25 09:24
L8	29	(front or top or upper or first or parent or higher) near (chip or die or ic) near3 (bottom or back or lower or second or child or daughter) near (chip or die or ic) near3 (bonded or joined or connection or connected or connecting or wirebond or wirebonded or interconnect$3 or wired) near5 (aperture or window or via or hole or opening or thruhole) near4 (substrate or interposer or carrier or pcb or pwb or wiring adj board or circuit adj board)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/25 09:26
L9	31	(US-20010004128-$ or US-20010036711-$ or US-20020047196-$ or US-20020074630-$ or US-20020079568-$ or US-20020127770-$ or US-20030025199-$ or US-20030085463-$ or US-20030207516-$ or US-20040009631-$ or US-20040084771-$ or US-20040159955-$ or US-20020109237-$).did. or (US-5477082-$ or US-5608262-$ or US-5869894-$ or US-5886412-$ or US-5949135-$ or US-6104089-$ or US-6343019-$ or US-6365963-$ or US-6388333-$ or US-6448506-$ or US-6452278-$ or US-6506633-$ or US-6659512-$ or US-6678167-$ or US-6693362-$ or US-6731015-$ or US-6791195-$).did. or (EP-1122786-$).did.	US-PGPUB; USPAT; EPO	OR	ON	2005/05/25 09:34
L10	1	"6441495".pn.	US-PGPUB; USPAT; EPO	OR	ON	2005/05/25 09:34
S1	346	(multidie or multi-die or stacked near die) near2 package	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/25 08:56
S2	7	("20020109226" | "5586010" | "5814877" | "6084308" | "6160705" | "6380631" | "6452278").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/05/19 16:58
S3	13	"5506383".pn. "5541450".pn. "5639695".pn. "20010004128" "6172419".pn. "6201302" .pn. "6326696".pn. "20020064900" "6365963" .pn. "6414381" .pn. "6452278" .pn. "6469395" .pn. "20020142513"	US-PGPUB; USPAT; USOCR	OR	ON	2005/05/19 16:59

S4	3	"5869894".pn. "5949135".pn. "6506633".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2005/05/19 16:59
S5	2252	(interposer or substrate or package) near3 (recess or opening or indent or aperture or recessed or depression or depressed or receptacle or socket) near2 (die or ic)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/23 08:45
S6	201	(interposer or substrate or package) near2 (recess or opening or indent or aperture or recessed or depression or depressed or receptacle) near2 (die or ic) and (multidie or (plural or plurality or multiple or multi or second or secondary) near (die or ic))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/23 09:34
S7	161	(interposer or substrate or package) near2 (cavity) near2 (die or ic) and (multidie or (plural or plurality or multiple or multi or second or secondary) near (die or ic))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/23 10:21
S8	399	257/723.ccor.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/23 10:33
S9	91	257/723.ccor. and (die or ic or chip) near2 (recess or recessed or cavity or hole or aperture or opening or receptacle or socket or depression or depressed or indent or indentation or trench)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/23 10:59
S10	32	257/724.ccor. and (die or ic or chip) near2 (recess or recessed or cavity or hole or aperture or opening or receptacle or socket or depression or depressed or indent or indentation or trench)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/24 10:01
S11	107	257/777.ccor. and (die or ic or chip) near2 (recess or recessed or cavity or hole or aperture or opening or receptacle or socket or depression or depressed or indent or indentation or trench)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/25 09:18
S12	95	438/107.ccor. and (die or ic or chip) near2 (recess or recessed or cavity or hole or aperture or opening or receptacle or socket or depression or depressed or indent or indentation or trench)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/23 11:23
S13	24	(US-20010004128-$ or US-20030025199-$ or US-20030207516-$ or US-20040009631-$ or US-20040084771-$ or US-20020079568-$ or US-20030085463-$ or US-20020047196-$ or US-20020127770-$).did. or (US-5869894-$ or US-5949135-$ or US-6365963-$ or US-6452278-$ or US-6506633-$ or US-6731015-$ or US-6678167-$ or US-6448506-$ or US-6343019-$ or US-5886412-$ or US-6104089-$ or US-5608262-$ or US-6693362-$ or US-6659512-$).did. or (EP-1122786-$).did.	US-PGPUB; USPAT; EPO	OR	ON	2005/05/23 11:35
S14	2	("5614766" | "5744862").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/05/23 14:40
S15	22	("5949135").URPN.	USPAT	OR	ON	2005/05/23 14:41
S16	11	("6104089").URPN.	USPAT	OR	ON	2005/05/23 14:44

S17	36	("4649418" | "4725924" | "4731645" | "4748495" | "4931853" | "4991000" | "4992849" | "4992850" | "4996587" | "5016138" | "5041396" | "5045921" | "5096852" | "5102831" | "5107328" | "5137836" | "5182632" | "5239198" | "5255156" | "5280192" | "5280193" | "5418687" | "5438216" | "5465470" | "5477067" | "5477082" | "5480840" | "5495398" | "5502289" | "5535101" | "5674785" | "5773320" | "5777391" | "5891753" | "5894107" | "6013946").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/05/23 14:50
S18	586	(interposer) and (opening or aperture or hole or thruhole or cavity) near3 (wirebond or wire or wiring or bond)	US-PGPUB; USPAT; USOCR	OR	ON	2005/05/23 14:51
S19	366	(interposer) and (opening or aperture or hole or thruhole or cavity) near3 (wirebond or wire or wiring or bond) and (multichip or (stacked or plural or multi or multiple or plurality or second or two or third or three) near (chip or die or ic))	US-PGPUB; USPAT; USOCR	OR	ON	2005/05/23 15:58
S20	1838	(interposer or circuit near board or wiring near board or substrate) near10 (top or upper or above) near (chip or die or ic) near10 (bottom or below or lower or under or underneath) near (chip or die or ic)	US-PGPUB; USPAT; USOCR	OR	ON	2005/05/23 15:59
S21	42	(interposer or circuit near board or wiring near board or substrate) near10 (top or upper or above) near (chip or die or ic) near10 (bottom or below or lower or under or underneath) near (chip or die or ic) and (aperture or opening or hole) near3 (wire or wiring or wirebonds) near5 (chip or die or ic)	US-PGPUB; USPAT; USOCR	OR	ON	2005/05/23 16:11
S22	8	("5355283" | "5768774" | "5801432" | "6127724" | "6380615" | "6507102" | "6614660" | "6713856").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/05/23 16:04
S23	6	("6218731" | "6265763" | "6281578" | "6396116" | "6414396" | "6458625").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/05/23 16:06
S24	9	(interposer or circuit near board or wiring near board or substrate) near10 (front or frontside) near (chip or die or ic) near10 (back or backside) near (chip or die or ic) and (aperture or opening or hole or window) near3 (wire or wiring or wirebonds) near5 (chip or die or ic)	US-PGPUB; USPAT; USOCR	OR	ON	2005/05/23 16:12
S25	6	(interposer) near10 (aperture or opening or hole or window) near3 ((wire or wiring) near (bond or bonding) or wirebonds) near5 (chip or die or ic)	US-PGPUB; USPAT; USOCR	OR	ON	2005/05/23 16:13
S26	12	("5412538" | "5528222" | "5566441" | "5600175" | "5652462" | "5661339" | "5682143" | "5696395" | "5754408" | "5818698" | "5875100" | "5998860").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/05/23 16:13
S27	230	(interposer or substrate) near10 (aperture or opening or hole or window) near3 ((wire or wiring) near (bond or bonding) or wirebonds) near5 (chip or die or ic)	US-PGPUB; USPAT; USOCR	OR	ON	2005/05/23 16:14
S28	485	257/777.ccor.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/24 09:06
S29	4573	(interposer or carrier near substrate) and (mcm or multichip or multidie or (plural or multiple or stacked or plurality or multi or bottom or back) near2 (chip or die or ic or module))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/24 09:07
S30	162	(interposer or carrier near substrate) and (mcm or multichip or multidie or (plural or multiple or stacked or plurality or multi or bottom or back) near2 (chip or die or ic or module)) and (interposer or carrier or substrate) near2 (aperture or opening or recess or receptacle or window) near2 (chip or die or ic or wirebond or bonding near wire or wire near bond or pillar or interconnect)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/24 09:09
S31	7	("20020113304" | "20020130398" | "20020135080" | "20030025199" | "5523608" | "6057597" | "6353257").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/05/24 09:36

S32	31	(dual or double or two) near (side or sided) near2 interposer	US-PGPUB; USPAT; USOCR	OR	ON	2005/05/24 09:37
S33	28	(US-20010004128-$ or US-20010036711-$ or US-20020047196-$ or US-20020079568-$ or US-20020127770-$ or US-20030025199-$ or US-20030085463-$ or US-20030207516-$ or US-20040009631-$ or US-20040084771-$ or US-20020074630-$).did. or (US-5477082-$ or US-5608262-$ or US-5869894-$ or US-5886412-$ or US-5949135-$ or US-6104089-$ or US-6343019-$ or US-6365963-$ or US-6448506-$ or US-6452278-$ or US-6506633-$ or US-6659512-$ or US-6678167-$ or US-6693362-$ or US-6731015-$ or US-6388333-$).did. or (EP-1122786-$).did.	US-PGPUB; USPAT; EPO	OR	ON	2005/05/24 09:40
S34	121	257/778.ccor. and (die or ic or chip) near2 (recess or recessed or cavity or hole or aperture or opening or receptacle or socket or depression or depressed or indent or indentation or trench or window)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/24 10:35
S35	2	("5567981" | "5795818").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/05/24 10:23
S36	25	257/782.ccor. and (die or ic or chip) near2 (recess or recessed or cavity or hole or aperture or opening or receptacle or socket or depression or depressed or indent or indentation or trench or window)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/24 10:37
S37	769	interposer and (top or first or upper or above or front) near (chip or die or ic) and (bottom or back or second or lower or under or underneath or below or beneath) near (chip or die or ic)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/24 10:38
S38	35	interposer and (top or first or upper or above or front) near (chip or die or ic) and (bottom or back or second or lower or under or underneath or below or beneath) near (chip or die or ic) and (aperture or via or opening or hole or window) near2 (interposer) near3 (wiring or solder near ball or interconnect or connection or pillar or conductor or wire)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/24 10:39